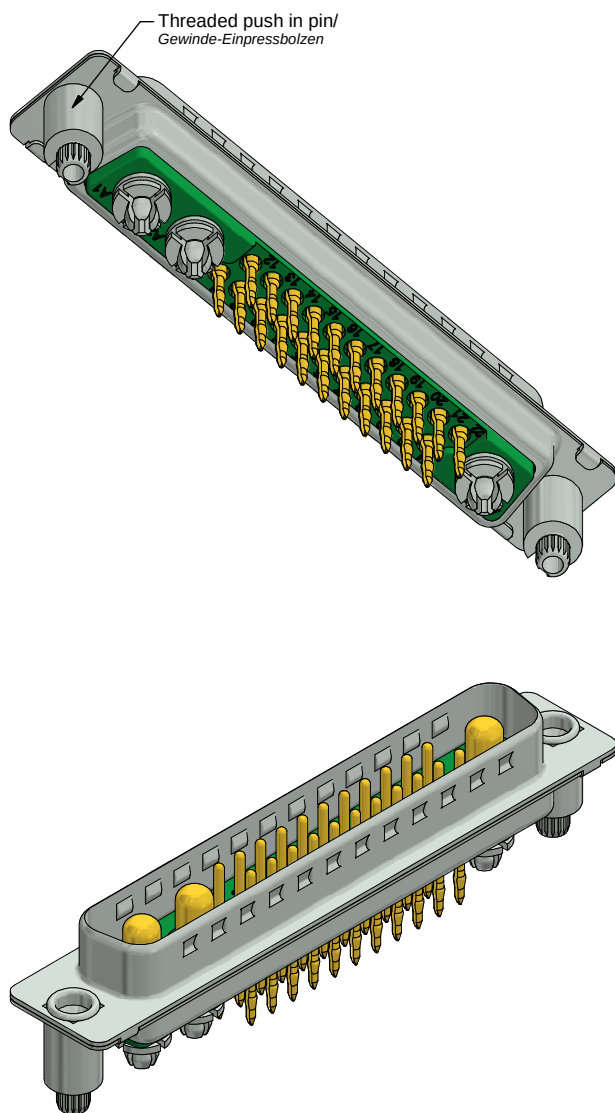




Technical specification/

Technische Daten:

Dielectric withstanding voltage/ Spannungsfestigkeit:	1000 V, 50 Hz 1 min.
Current rating/ Strombelastbarkeit:	Signal contact 7,5 A (UL), Signalkontakt 5 A (CSA,VDE) High power press-fit contact 30 A Hochstrom Press-Fit Kontakt
Insulation resistance/ Isolationswiderstand:	≥ 5 GΩ
Temperature range/ Temperaturbereich:	- 55 °C ... + 125 °C
Mating cycles/ Steckzyklen:	Quality class 3 = 50 Gütestufe 3

Materials/

Werkstoffe:

Signal contact/ Signalkontakt:	Cu alloy, Au over Ni
High power press-fit contact/ Hochstrom Press-Fit Kontakt:	Cu alloy, mating side/Steckseite Au over Ni press-fit area / Press-Fit Bereich Sn over Ni
Insulator/ Isolierkörper:	PBT GF UL 94 V-0, green/grün
Shell/ Gehäuse:	Steel, Sn over Ni
Threaded push in pin/ Gewinde-Einpressbolzen:	Cu alloy, Sn

Installation specification/

Montagedaten:

Recommended torque value for thread/ Empfohlenes Drehmoment für Gewinde:	max. 6 in.LB/ max. 67 Ncm
PCB thickness/ Leiterplatten Dicke:	min. 2,0 mm

Part no. / Part marked Art.-Nr. / Bedruckung:	3025W3PAPP1W20X	Contact plating/ Kontakt Veredelung:	Signal contact Signalkontakt:	gold flash over nickel Gold über Nickel
		High power press-fit contact 30 A/ Hochstrom Press-Fit Kontakt 30 A:	plating, mating side: Veredelung, Steckseite: plating, press-fit area: Veredelung, Press-Fit Bereich:	30 µin hard gold over min. 50 µin nickel 30 µin Gold über min. 50 µin Nickel tin over nickel Zinn über Nickel
Index: b Ä7466 13.09.18 KHE	Scale/ Maßstab: 2:1	 dim. in mm		
Status: InBearbeitung		drawn/ gez. appd./ gepr.:	Date/ Datum: 05.09.2018 06.09.2018	Name: Unkrüer Henneboel
RoHS compliant/ konform				
		dwg no / Z.-nr.:	13K1A5685	DIN-A3
		1 / 2		

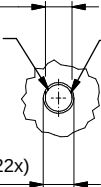
Y (5 : 1)

Finished hole/
Endloch: $\varnothing 1^{+0,09}_{-0,06}$ (22x)

Copper thickness/
Cu Schichtdicke:
25 μ m (1000 μ in) min.

Tin thickness/
Sn Schichtdicke:
15 μ m (600 μ in) max.

Drilled hole/
Bohrloch $\varnothing 1,15 \pm 0,025$ (22x)

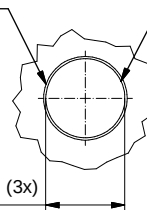


X (5 : 1)

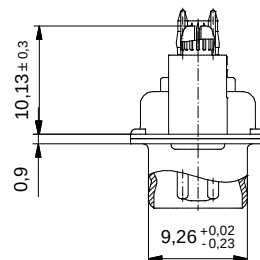
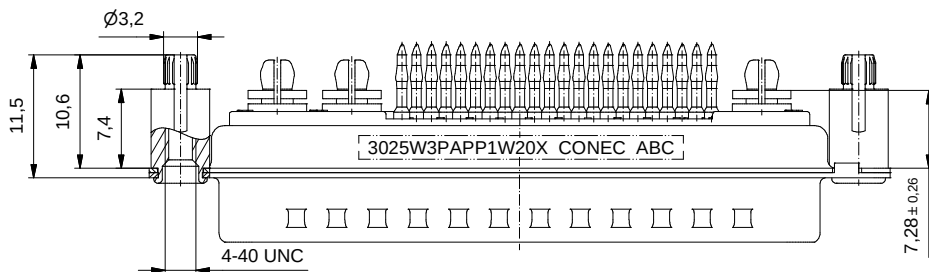
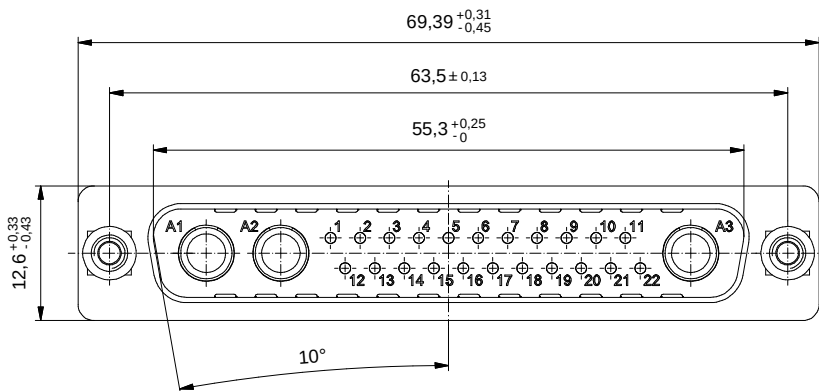
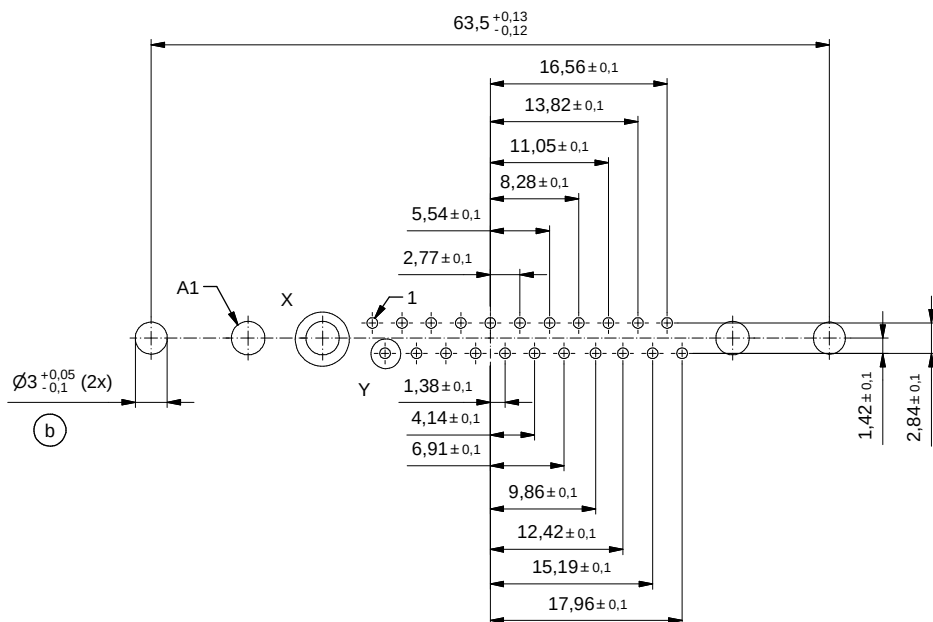
Copper thickness/
Cu Schichtdicke:
25 μ m (1000 μ in) min.

Tin thickness/
Sn Schichtdicke:
15 μ m (600 μ in) max.

Finished hole after reflow/
Endloch: $\varnothing 2,96$ min. - $\varnothing 3,11$ max. (3x)



PCB hole drillings
(PCB top side)
Leiterplattenbohrbild
(Leiterplatten Oberseite)



		 dim. in mm		D-SUB Combination Male 25W3P press-fit with threaded push in pin		
		drawn/ gez.	Date/Datum 05.09.2018	Name Unkrüer	D-SUB Combination Stifteleiste 25W3P Press-Fit mit Gewinde-Einpressbolzen	
		appd./ gepr.	06.09.2018	Henneboel		
Index: b Ä7466 13.09.18 KHE		scale/Maßstab: 2:1			dwg no / Z.-nr.: 13K1A5685	DIN- A3
Status: InBearbeitung						
RoHS compliant/ konform						2 / 2



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